## **AMENDMENTS TO THE CLAIMS:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-6 are cancelled.

- 7. (New) A die cleaning method for removing a forming-material from a die used in forming the forming-material constituted of clay containing a binder, characterized by comprising the steps of: removing a part or all of the binder contained in the forming-material from the die; and removing the forming-material from the die.
- 8. (New) The die cleaning method according to claim 7, wherein the step of removing a part or all of the binder is performed by heating the die.
- 9. (New) The die cleaning method according to claim 8, wherein a heating temperature is in a range of 200 to 500°C.
- 10. (New) The die cleaning method according to claim 7, wherein the step of removing the forming-material is performed by spraying a fluid to the die at a pressure of 40 kg/cm<sup>2</sup> or less.
- 11. (New) The die cleaning method according to claim 7, wherein the die includes a member constituted of cemented carbide.
- 12. (New) The die cleaning method according to claim 7, wherein the die includes a member having slits.